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STS9NH3LL

N-channel 30 V - 0.018 Ω - 9 A - SO-8 low gate charge STripFETTM III Power MOSFET

Features

Туре	V _{DSS}	R _{DS(on)} max	I _D
STS9NH3LL	30 V	$0.022~\Omega$	9 A

- Optimal R_{DS(on)} x Qg trade-off @ 4.5 V
- Conduction losses reduced
- Switching losses reduced

Application

Switching applications

Description

This application specific Power MOSFET is the third generation of STMicroelectronics unique "single feature size" strip-based process. The resulting transistor shows the best trade-off between on-resistance and gate charge. When used as high and low side in buck regulators, it gives the best performance in terms of both conduction and switching losses. This is extremely important for motherboards where fast switching and high efficiency are of paramount importance.

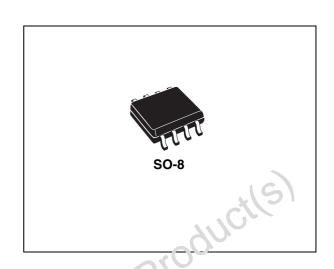


Figure 1. Internal schematic diagram

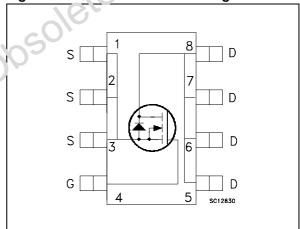


Table Device summary

	Order code	Marking	Package	Packaging
1	STS9NH3LL	S9NH3LL	SO-8	Tape & reel

Contents STS9NH3LL

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STS9NH3LL Electrical ratings

1 Electrical ratings

Table 2. Absolute maximum ratings

Symbol	Parameter	Value	Unit
V _{DS}	Drain-source voltage (V _{GS} = 0)	30	V
V _{GS}	Gate-source voltage	±16	V
I _D	Drain current (continuous) at T _C = 25 °C	9	Α
I _D	Drain current (continuous) at T _C = 100 °C	6	А
I _{DM} ⁽¹⁾	Drain current (pulsed)	36	А
P _{TOT}	Total dissipation at T _C = 25 °C	2.5	W
E _{AS} (2)	Single pulse avalanche energy	100	mJ
T _J T _{stg}	Operating junction temperature Storage temperature	-55 to 150	°C

^{1.} Pulse width limited by safe operating area

Table 3. Thermal data

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Symbol	Parameter	Value	Unit
R _{thj-amb} ⁽¹⁾	Thermal resistance junction-ambient max	50	°C/W

^{1.} When mounted on 1 inch² FR-4 board, 2oz Cu (t < 10 sec.)

^{2.} Starting $T_J = 25$ °C, $I_D = 6$ A.

Electrical characteristics STS9NH3LL

2 Electrical characteristics

(T_{CASE}=25°C unless otherwise specified)

Table 4. On/off states

Symbol	ol Parameter Test conditions		Min.	Тур.	Max.	Unit
V _{(BR)DSS}	Drain-source breakdown voltage	$I_D = 250 \mu A, V_{GS} = 0$	30			V
I _{DSS}	Zero gate voltage drain current (V _{GS} = 0)	V _{DS} = Max rating V _{DS} = Max rating @ 125 °C			1 10	μ Α μ Α
I _{GSS}	Gate body leakage current (V _{DS} = 0)	V _{GS} = ±16 V			±100	nA
V _{GS(th)}	Gate threshold voltage	$V_{DS} = V_{GS}$, $I_{D} = 250 \mu A$	1			٧
R _{DS(on)}	Static drain-source on resistance	V_{GS} = 10 V, I_{D} = 4.5 A V_{GS} = 4.5 V, I_{D} = 4.5 A		0.018 0.020	0.022 0.025	Ω

Table 5. Dynamic

Symbol	Parameter	Test conditions	Min.	Тур.	Max.	Unit
g _{fs} (1)	Forward transconductance	$V_{DS} = 10 \text{ V}, I_D = 4.5 \text{ A}$		8.5		S
C _{iss} C _{oss} C _{rss}	Input capacitance Output capacitance Reverse transfer capacitance	V _{DS} = 25 V, f=1 MHz, V _{GS} =0		857 147 20		pF pF pF
Q _g Q _{gs} Q _{gd}	Total gate charge Gate-source charge Gate-drain charge	V_{DD} = 15 V, I_{D} = 9 A V_{GS} = 4.5 V, (see Figure 16)		7.0 2.5 2.3	10	nC nC nC

^{1.} Pulsed: pulse duration=300 μs, duty cycle 1.5%

Table 6. **Switching times**

Symbol	Parameter	Test conditions	Min.	Тур.	Max.	Unit
t _{d(on)}	Turn-on delay time Rise time	V_{DD} =15 V, I_{D} = 4.5 A, R_{G} = 4.7 Ω , V_{GS} = 4.5 V (see Figure 15)		12 14.5		ns ns
t _{d(off)}	Turn-off delay time Fall time	V_{DD} =15 V, I_{D} = 4.5 A, R_{G} = 4.7 Ω , V_{GS} = 4.5 V (see Figure 15)		23 8		ns ns

Table 7. Source drain diode

e-drain current e-drain current		Min.	Тур.	Max.	Unit
ed)				9 36	A A
rd on voltage	I _{SD} = 4.5 A, V _{GS} =0		. (1.5	V
se recovery charge	I_{SD} = 9 A, di/dt = 100 A/µs, V_{DD} = 15 V, Tj=150 °C (see Figure 17)	Ó	15 5.7 0.76		ns nC A
	06501				
Jucile)					
	ration=300 μs, duty cycle	rse recovery time se recovery charge rse recovery current $I_{SD}=9$ A, di/dt = 100 A/ μ s, $V_{DD}=15$ V, Tj=150 °C (see Figure 17) red by safe operating area rration=300 μ s, duty cycle 1.5%	rse recovery time $I_{SD} = 9 \text{ A}$, di/dt = 100 A/ μ s, $V_{DD} = 15 \text{ V}$, Tj=150 °C (see Figure 17) red by safe operating area arration=300 μ s, duty cycle 1.5%	rse recovery time $I_{SD} = 9 \text{ A}$, $di/dt = 100 \text{ A/µs}$, $V_{DD} = 15 \text{ V}$, $T_{J} = 150 \text{ °C}$ $(see \ Figure \ 17)$ 0.76 $(see \ Figure \ 17)$ 0.76 $(see \ Figure \ 17)$ $(see \ Figure \ 17)$	rse recovery time $I_{SD}=9$ A, di/dt = 100 A/ μ s, $V_{DD}=15$ V, Tj=150 °C $(see\ Figure\ 17)$ 0.76 se recovery current $(see\ Figure\ 17)$ 0.76 ed by safe operating area ration=300 μ s, duty cycle 1.5%

Electrical characteristics STS9NH3LL

2.1 Electrical characteristics (curves)

Figure 2. Safe operating area

Figure 3. Thermal impedance

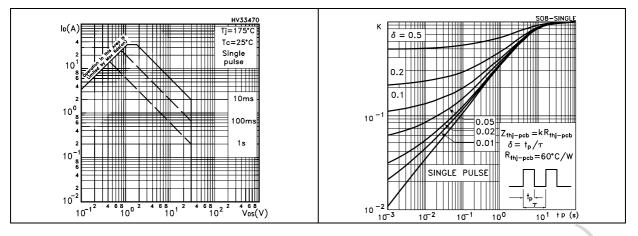


Figure 4. Output characteristics

Figure 5. Transfer characteristics

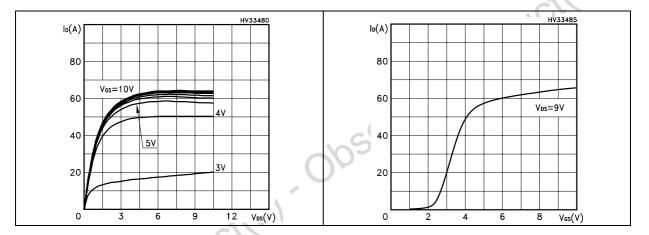
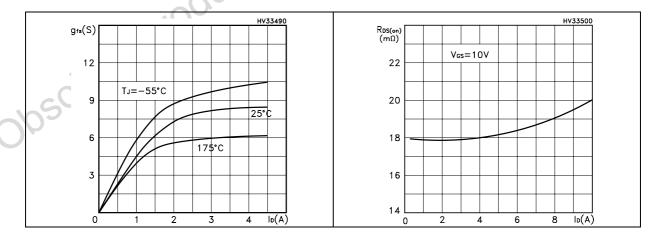


Figure 6. Transconductance

Figure 7. Static drain-source on resistance



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Figure 8. Gate charge vs gate-source voltage Figure 9. Capacitance variations

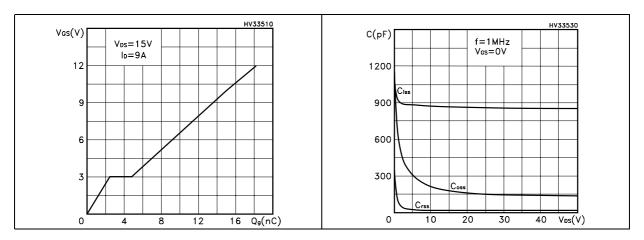


Figure 10. Normalized gate threshold voltage vs temperature

Figure 11. Normalized on resistance vs temperature

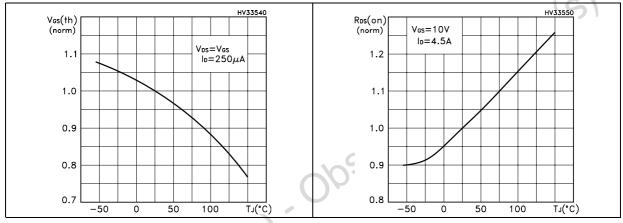
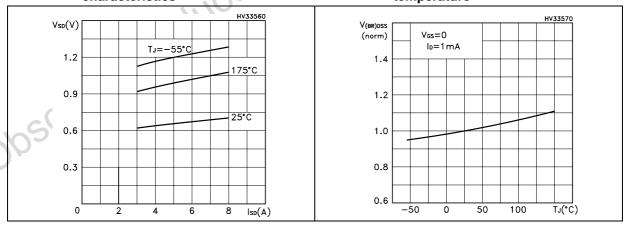


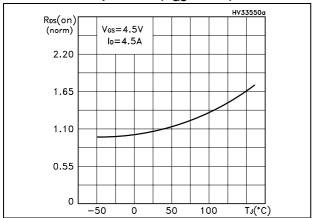
Figure 12. Source-drain diode forward characteristics

Figure 13. Normalized breakdown voltage vs temperature



Electrical characteristics STS9NH3LL

Figure 14. Normalized on resistance vs temperature ($V_{GS} = 4.5V$)



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STS9NH3LL Test circuit

3 Test circuit

Figure 15. Switching times test circuit for resistive load

Figure 16. Gate charge test circuit

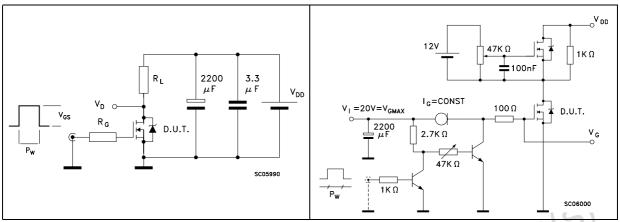


Figure 17. Test circuit for inductive load switching and diode recovery times

Figure 18. Unclamped inductive load test circuit

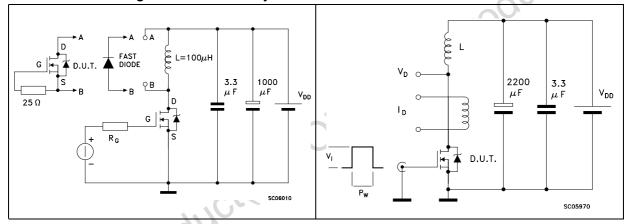
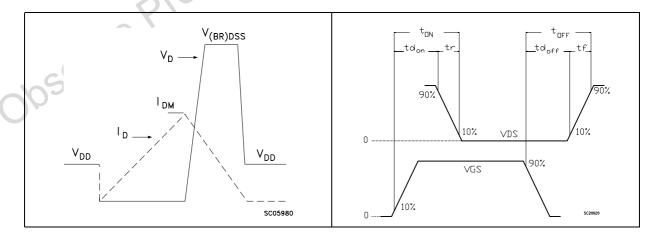


Figure 19. Unclamped inductive waveform

Figure 20. Switching time waveform



4 Package mechanical data

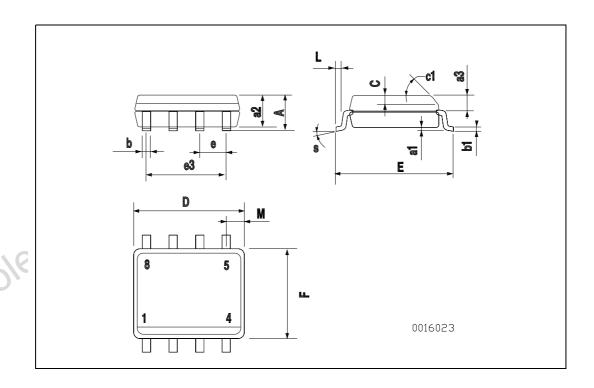
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SO-8 MECHANICAL DATA

DIM.		mm.			inch	inch		
DIM.	MIN.	TYP	MAX.	MIN.	TYP.	MAX.		
Α			1.75			0.068		
a1	0.1		0.25	0.003		0.009		
a2			1.65			0.064		
а3	0.65		0.85	0.025		0.033		
b	0.35		0.48	0.013		0.018		
b1	0.19		0.25	0.007		0.010		
С	0.25		0.5	0.010		0.019		
c1			45 ((typ.)				
D	4.8		5.0	0.188		0.196		
E	5.8		6.2	0.228		0.244		
е		1.27			0.050			
e3		3.81			0.150			
F	3.8		4.0	0.14		0.157		
L	0.4		1.27	0.015		0.050		
М			0.6			0.023		
S		•	8 (n	nax.)	•	•		



Revision history STS9NH3LL

5 Revision history

Table 8. Document revision history

Date	Revision	Changes
24-Jul-2006	1	Initial release.
15-May-2007	2	Update on <i>Table 2</i> .
12-Dec-2007	3	 Inserted Figure 14: Normalized on resistance vs temperature (V_{GS} = 4.5V) Inserted new E_{AS} value on Table 2.

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